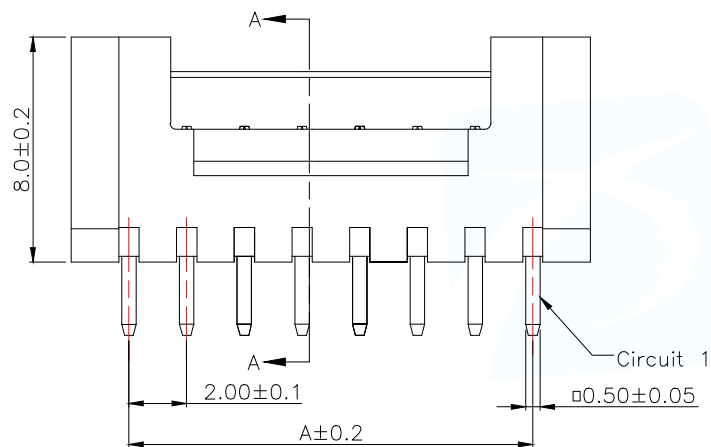
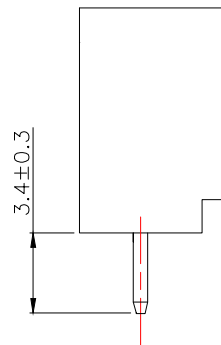
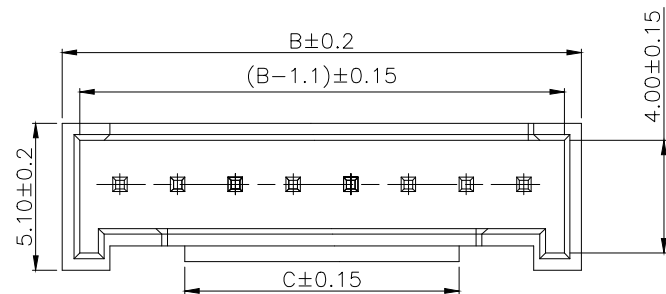
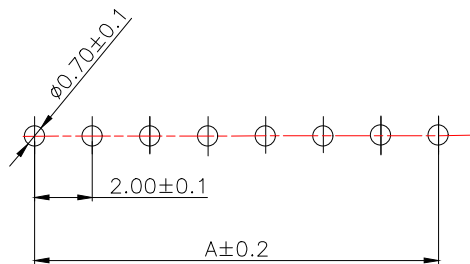


SECTION A-A

SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

技术要求:

1. 塑件材料: PA66 (UL-94V-0)
2. 接触件: 黄铜镀锡
3. 接触电阻: $\leq 10\text{m}\Omega$
4. 绝缘电阻: $\geq 100\text{M}\Omega$
5. 额定电压: 250V AC DC
6. 额定电流: 2.0A AC DC
7. 耐压: 能承受 1000V AC/Minute
8. 工作温度: $-25^{\circ}\sim+85^{\circ}$
9. 可焊性试验: 浸锡面积 $\geq 95\%$ 温度 $235 \pm 5^{\circ}\text{C}$ 时间 $2.5 \pm 0.5\text{s}$
10. 铅和镉等六大有害物质含量要符合环保要求。

Part No	Pin	A	B	C
WAFER-HY2.0-2PZZ	2	2.00	6.00	3.00
WAFER-HY2.0-3PZZ	3	4.00	8.00	3.30
WAFER-HY2.0-4PZZ	4	6.00	10.00	4.00
WAFER-HY2.0-5PZZ	5	8.00	12.00	6.00
WAFER-HY2.0-6PZZ	6	10.00	14.00	8.00
WAFER-HY2.0-7PZZ	7	12.00	16.00	10.00
WAFER-HY2.0-8PZZ	8	14.00	18.00	12.00
WAFER-HY2.0-9PZZ	9	16.00	20.00	14.00
WAFER-HY2.0-10PZZ	10	18.00	22.00	16.00
WAFER-HY2.0-11PZZ	11	20.00	24.00	18.00
WAFER-HY2.0-12PZZ	12	22.00	26.00	20.00
WAFER-HY2.0-13PZZ	13	24.00	28.00	22.00
WAFER-HY2.0-14PZZ	14	26.00	30.00	24.00
WAFER-HY2.0-15PZZ	15	28.00	32.00	26.00

2	端子Contact	黄铜	N*1	电镀(锡): 整个表面镀底镍 30u"MIN, 再镀锡80u"MIN
1	基座Wafer	LCP(UL94V-0)	1	白色

序号	名称	材料	数量	备注
----	----	----	----	----

MANUFACTURE DWG

东莞市讯普电子科技有限公司
DongGuan XunPu Electronics Co., LtdUNLESS OTHERWISE
SPECIFIED TOLERANCES

TITLE:

WAFER HY2.0MM 直针

PAR WAFER-HY2.0-NPZZ

DWN

CHKD

APVD

SCALE:1:1 UNIT:MM

SIZE:A4 SHEET:1F1



REV:A

DECIMALS:

.X±0.20

.XX±0.10

.XXX±0.05

ANGLES:

±2°

CUSTOMER COPY